

ABSTRACT OF THE DISCLOSURE

There is disclosed a semiconductor device comprising a first wire and a pad portion thereof provided in a portion from an upper surface to an inner portion of a first insulation film provided above a substrate, a second insulation film provided on the first insulation film and the first wire, a second wire provided to be exposed from an upper surface of the second insulation film in an upper portion of the pad portion of the first wire, and a contact plug provided to reach an inner portion of the pad portion of the first wire from an undersurface of the second wire.